

App. Ser. No. 10/735,698  
Amendment dated Apr. 19, 2007  
Reply to Office action dated Jan. 19, 2007

Docket No. AB-1625-2C US  
(Ref. No. LW5009US(DV)(CA))

**Amendments to the Claims:**

The following listing of claims will replace all prior versions and listings of claims in the Application:

**Listing of Claims:**

1. – 12. (cancelled)
13. (previously presented) A display device, comprising:
  - a mold frame, including a series of optical sheets;
  - a bottom chassis assembled to said mold frame;
  - a top chassis assembled to said mold frame;
  - a display panel positioned between said bottom chassis and said top chassis;
  - a printed circuit board (PCB) connected to said display panel, the PCB being disposed below the bottom chassis; and,
  - a grounding protrusion formed on an upper surface of said PCB,wherein the grounding protrusion is protruded higher than any other components formed on the surface, and the ground protrusion is disposed in contact with the bottom chassis.
14. (previously presented) The display device according to claim 13, wherein said mold frame accommodates a lamp assembly and a reflector.
15. (previously presented) The display device according to claim 14, wherein said display panel is positioned onto said optical sheets.
16. (previously presented) The display device according to claim 15, wherein said PCB is connected to said display panel via a tape carrier package (TCP), and fixed to said bottom chassis by a fixing means.
17. (previously presented) The display device according to claim 16, wherein said grounding protrusion is formed on said PCB where a signal transmission pattern is not formed.
18. (currently amended) A display device, comprising:
  - a chassis;
  - a display panel assembled with the chassis;

a printed circuit board (PCB) connected to the display panel, the PCB being disposed below the chassis; and,

a ground protrusion formed on an upper surface of the PCB,  
wherein the chassis is disposed between the display panel and the PCB and  
the ground protrusion is protruded higher than any other components formed on the upper  
surface of the PCB and ~~the ground protrusion~~ is disposed in contact with a lower surface of the  
chassis.

19. (previously presented) The display device of claim 18, wherein the PCB comprises a grounding pattern, the ground protrusion being protruded from the grounding pattern.

20. (previously presented) The display device of claim 19, wherein the PCB further comprises a driving integrated circuit (IC) and a signal transmission pattern.

21. (cancelled)

22. (previously presented) The display device of claim 19, wherein the PCB is attached on the chassis.

23. (previously presented) The display device of claim 22, wherein the PCB has a screw hole and is attached to the chassis by a screw.

24. (previously presented) The display device of claim 23, wherein the screw hole is formed on a corner of the PCB.

25. (previously presented) The display device of claim 22, wherein the ground protrusion is in direct contact with the chassis.

26. (previously presented) The display device of claim 18, further comprising a tape carrier package (TCP) coupled between the display panel and the PCB.

27. (previously presented) The display device of claim 18, further comprising a mold frame assembled with the chassis.

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28. (previously presented) The display device of claim 18, further comprising a back-light assembly unit.

29. (previously presented) The display device of claim 28, wherein the backlight assembly unit comprises a lamp, a reflector and an optical sheet.

30. (previously presented) The display device of claim 29, wherein the backlight assembly unit further comprises a light guiding plate.

31. (previously presented) The display device of claim 19, wherein the PCB further comprises a via hole.

32. (currently amended) A display device, comprising:  
a mold frame, including a series of optical sheets;  
a bottom chassis assembled to said mold frame;  
a top chassis assembled to said mold frame;  
a display panel positioned between said bottom chassis and said top chassis;  
a printed circuit board (PCB) disposed below and connected to said bottom chassis; and,  
a grounding protrusion formed on an upper surface of said PCB,  
wherein the ground protrusion is connected to the bottom chassis.

33. (currently amended) A display device, comprising:  
a chassis;  
a display panel assembled with the chassis;  
a printed circuit board (PCB) disposed below the chassis and connected to the display panel; and,  
a ground protrusion formed on a surface of the PCB, wherein the chassis is disposed between the display panel and the PCB,  
~~wherein~~ the ground protrusion is protruded higher than any other components formed on the surface, and  
~~wherein~~ the ground protrusion protrudes ~~is protruded~~ toward the chassis and makes contact with the chassis.